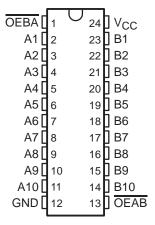
SCAS309F - MARCH 1993 - REVISED JUNE 1998

- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 2 V at V_{CC} = 3.3 V, T_A = 25°C
- Power Off Disables Outputs, Permitting Live Insertion
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages

DB, DW, OR PW PACKAGE (TOP VIEW)



description

This 10-bit bus transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVC861A is designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing.

This device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and OEBA) inputs.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVC861A is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

INP	UTS	OPERATION
OEAB	OEBA	OPERATION
L	Н	A data to B bus
Н	L	B data to A bus
Н	Н	Isolation
L	L	Latch A and B (A = B)

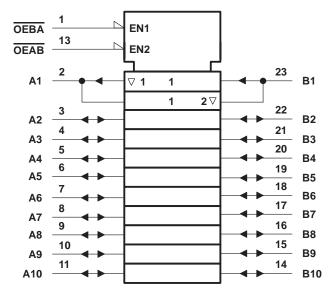


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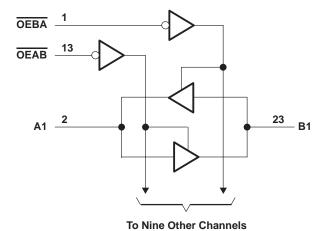


logic symbol†



 $[\]ensuremath{^{\dagger}}$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



TEXAS INSTRUMENTS

SCAS309F - MARCH 1993 - REVISED JUNE 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 6.5 V
Input voltage range, V _I : (see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high-impedance or power-off state, VO	
(see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3): DB package	104°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of $V_{\hbox{\scriptsize CC}}$ is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
\/aa	Supply voltage	Operating	1.65	3.6	V	
VCC	Supply voltage Dat	Data retention only	1.5		V	
	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}			
V_{IH}		gh-level input voltage $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$			V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}		
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
٧ _I	Input voltage		0	5.5	V	
\/-	Output voltage	High or low state	0	Vcc	V	
VO	Output voltage	3 state	0	5.5	V	
	High-level output current	V _{CC} = 1.65 V		-4		
la		V _{CC} = 2.3 V		-8	mA	
IOH		$V_{CC} = 2.7 \text{ V}$		-12		
		V _{CC} = 3 V		-24		
	Low-level output current	V _{CC} = 1.65 V		4		
lai		V _{CC} = 2.3 V		8	mA	
lOL		V _{CC} = 2.7 V		12	mA	
		V _{CC} = 3 V		24	<u> </u>	
Δt/Δν	Input transition rise or fall rate		0	10	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCAS309F - MARCH 1993 - REVISED JUNE 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAI	RAMETER	TEST CONDITI	Vcc	MIN	TYP [†]	MAX	UNIT	
		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} -0.2				
		I _{OH} = -4 mA	1.65 V	1.2				
\/o		I _{OH} = -8 mA	2.3 V	1.7			٧	
VOH		10.1. — 12.mA	104		2.2			
		IOH = -12 mA		3 V	2.4			
		I _{OH} = -24 mA	3 V	2.2				
		I _{OL} = 100 μA	1.65 V to 3.6 V			0.2		
		I _{OL} = 4 mA	1.65 V			0.45	V	
VOL		I _{OL} = 8 mA	2.3 V			0.7		
		I _{OL} = 12 mA	2.7 V			0.4		
		I _{OL} = 24 mA	3 V			0.55		
IĮ	Control inputs	V _I = 0 to 5.5 V		3.6 V			±5	μΑ
l _{off}		V _I or V _O = 5.5 V		0			±10	μΑ
loz‡		V _O = 0 to 5.5 V		3.6 V			±10	μΑ
Icc		V _I = V _{CC} or GND		0.014			10	
		3.6 V ≤ V _I ≤ 5.5 V§	IO = 0	3.6 V	10		10	μΑ
ΔlCC		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND		2.7 V to 3.6 V			500	μΑ
Ci	Control inputs	V _I = V _{CC} or GND		3.3 V		5		pF
C _{io}	A or B ports	$V_O = V_{CC}$ or GND		3.3 V		7		pF

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
	(INFOT)		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	A or B	B or A	¶	¶	¶	¶		6.8	1.3	6.4	ns
t _{en}	OEAB or OEBA	A or B	¶	¶	¶	¶		8.2	1	7	ns
^t dis	OEAB or OEBA	A or B	¶	¶	¶	¶		6.6	1.7	5.9	ns
t _{sk(o)} #						·				1	ns

This information was not available at the time of publication.

operating characteristics, T_A = 25°C

PARAMETER			TEST CONDITIONS	V _{CC} = 1.8 V ± 0.15 V	V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT
			CONDITIONS	TYP	TYP	TYP	
Const	Power dissipation capacitance	Outputs enabled	f = 10 MHz	¶	¶	29	nE.
C _{pd}	per transceiver	Outputs disabled	f = 10 MHz	¶	¶	5	pF

 $[\]P$ This information was not available at the time of publication.

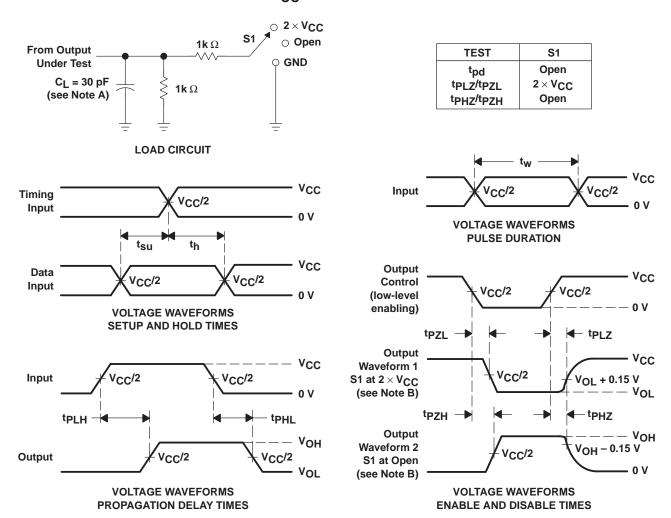


[‡] For I/O ports, the parameter IOZ includes the input leakage current.

[§] This applies in the disabled state only.

[#] Skew between any two outputs of the same package switching in the same direction

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$

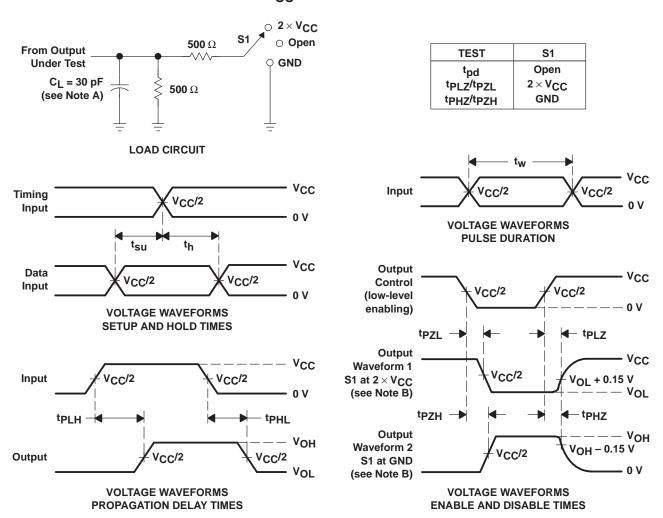


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



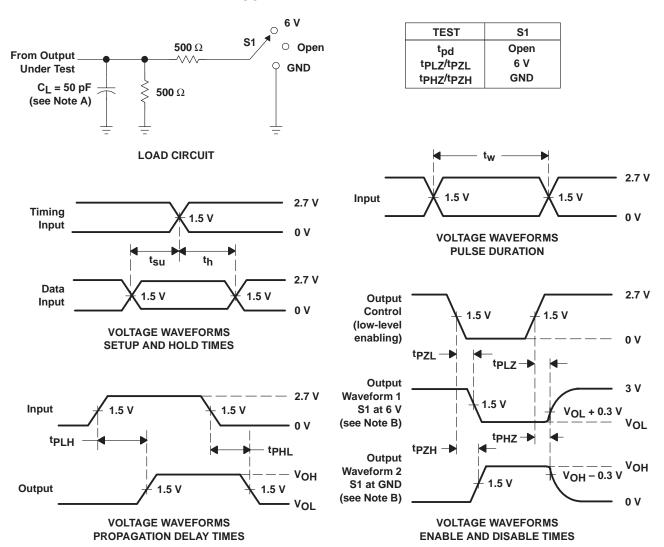
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpZL and tpZH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{\Omega} = 50 \Omega$, $t_{\Gamma} \leq$ 2.5 ns, $t_{\Gamma} \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

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